

# **Standard Rectifier Module**

=2x 800 V

190 A

 $V_{\mathsf{F}}$ 0.96 V

## Phase leg

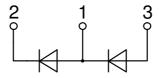
#### Part number

#### MDD172-08N1



Backside: isolated





### Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current

### **Applications:**

- Diode for main rectification
- For single and three phase bridge configurations
- Supplies for DC power equipment
- Input rectifiers for PWM inverter
- Battery DC power supplies
- Field supply for DC motors

### Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- · Reduced weight
- Advanced power cycling

#### Terms \_Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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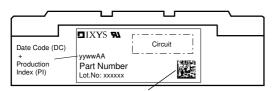




Rectifier				1	Ratings	s	
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V <sub>RSM</sub>	max. non-repetitive reverse bloc	cking voltage	$T_{VJ} = 25^{\circ}C$			900	V
$V_{RRM}$	max. repetitive reverse blocking	voltage	$T_{VJ} = 25^{\circ}C$			800	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 800 V	$T_{VJ} = 25^{\circ}C$			1	mA
		$V_R = 800 \text{ V}$	$T_{VJ} = 150$ °C			20	mA
V <sub>F</sub>	forward voltage drop	I <sub>F</sub> = 150 A	$T_{VJ} = 25^{\circ}C$			1.07	V
		$I_F = 300 A$				1.22	٧
		$I_F = 150 \text{ A}$	T <sub>VJ</sub> = 125°C			0.96	V
		$I_F = 300 A$				1.16	٧
I <sub>FAV</sub>	average forward current	T <sub>C</sub> = 100°C	$T_{VJ} = 150$ °C			190	Α
I F(RMS)	RMS forward current	180° sine				300	Α
V <sub>F0</sub>	threshold voltage		$T_{VJ} = 150$ °C			0.80	٧
r <sub>F</sub>	slope resistance } for power	loss calculation only				8.0	mΩ
R <sub>thJC</sub>	thermal resistance junction to ca	ase				0.21	K/W
R <sub>thCH</sub>	thermal resistance case to heats	sink			0.08		K/W
P <sub>tot</sub>	total power dissipation		$T_{C} = 25^{\circ}C$			600	W
I <sub>FSM</sub>	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			6.60	kA
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			7.13	kA
		t = 10 ms; (50 Hz), sine	T <sub>vJ</sub> = 150°C			5.61	kA
		t = 8,3  ms; (60 Hz), sine	$V_R = 0 V$			6.06	kA
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			217.8	kA2s
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			211.5	kA2s
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 150$ °C			157.4	kA2s
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			152.8	kA2s
C	junction capacitance	$V_{R} = 400 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^{\circ}C$		238		pF



Package Y4			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current	per terminal					300	Α
T <sub>VJ</sub>	virtual junction temperature				-40		150	°C
T <sub>op</sub>	operation temperature				-40		125	°C
T <sub>stg</sub>	storage temperature				-40		125	°C
Weight						150		g
M <sub>D</sub>	mounting torque				2.25		2.75	Nm
$\mathbf{M}_{_{\mathbf{T}}}$	terminal torque				4.5		5.5	Nm
d <sub>Spp/App</sub>	oroonago distanco on surfaco l	etriking dietanee through air	terminal to terminal	14.0	10.0			mm
$d_{Spb/Apb}$	creepage distance on surface   striking distance through air terminal to backside 16.		16.0	16.0			mm	
V	isolation voltage t =	t = 1 second			3600			٧
		$t = 1 \text{ minute}$ 50/60 Hz, RMS; IsoL $\leq 1 \text{ mA}$			3000			٧



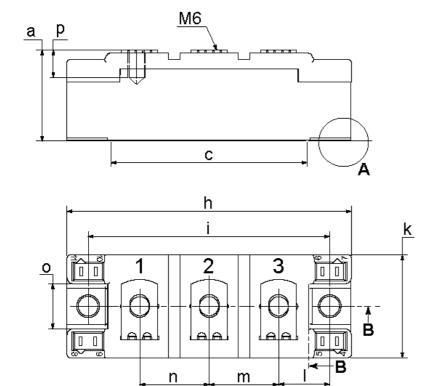
Data Matrix: part no. (1-19), DC + Pl (20-25), lot.no.# (26-31), blank (32), serial no.# (33-36)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MDD172-08N1	MDD172-08N1	Box	6	429694

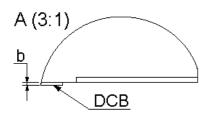
<b>Equivalent Circuits for Simulation</b>		* on die level	T <sub>vJ</sub> = 150 °C	
$I \rightarrow V_0$	$R_0$	Rectifier		
V <sub>0 max</sub>	threshold voltage	0.8		V
$R_{0 \text{ max}}$	slope resistance *	0.4		mΩ

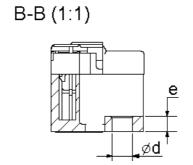


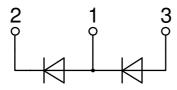
## Outlines Y4



Dim.	MIN [mm]	MAX [mm]	MIN [inch]	MAX [inch]
а	30.0	30.6	1.181	1.205
b	typ.	0.25	5 typ. 0.010	
С	64.0	65.0	2.520	2.559
d	6.5	7.0	0.256	0.275
е	4.9	5.1	0.193	0.201
h	93.5	94.5	3.681	3.720
i	79.5	80.5	3.130	3.169
k	33.4	34.0	1.315	1.339
I	16.7	17.3	0.657	0.681
m	22.7	23.3	0.894	0.917
n	22.7	23.3	0.894	0.917
0	14.0	15.0	0.551	0.591
р	typ.	10.5	typ. 0.413	

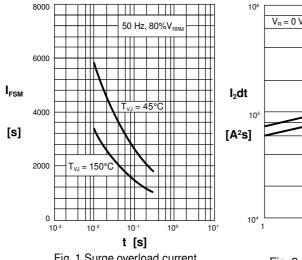


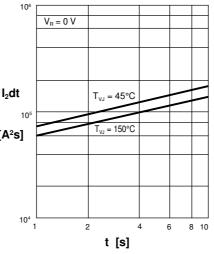






### Rectifier





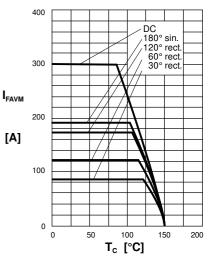


Fig. 1 Surge overload current  $I_{\text{FSM}}$ : Crest value, t: duration

Fig. 2 •1²dt versus time (1-10 ms)

Fig. 2a Maximum forward current at case temperature

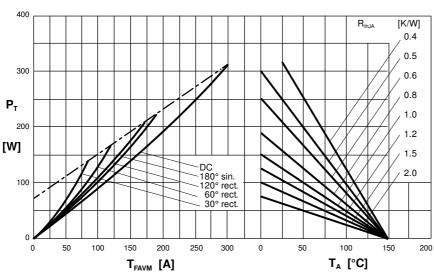
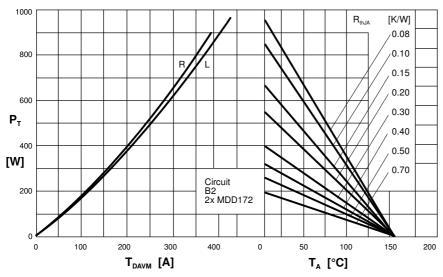


Fig. 3 Power dissipation vs. forward current and ambient temperature (per diode)



R = resistive load

L = inductive load

Fig. 4 Single phase rectifier bridge: Power dissipation vs. direct output current and ambient



#### Rectifier

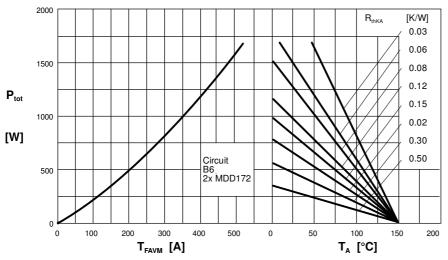


Fig. 5 Three phase rectifier bridge: Power dissipation vs. direct output current and ambient temperature

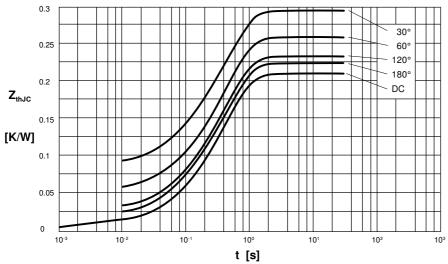


Fig. 6 Transient thermal impedance junction to case (per diode)

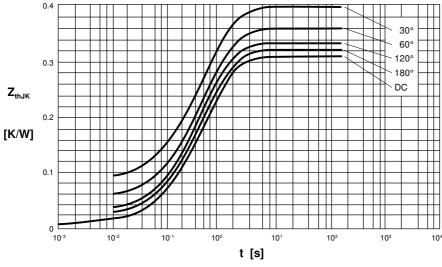


Fig. 7 Transient thermal impedance junction to heatsink (per diode)

R<sub>thJC</sub> for various conduction angles d:

d	$\mathbf{R}_{thJC}\left[K/W\right]$
DC	0.210
180°	0.223
120°	0.233
60°	0.260
30°	0.295

Constants for  $\boldsymbol{Z}_{\text{thJC}}$  calculation:

i	$\mathbf{R}_{thi}  [K/W]$	<b>t</b> <sub>i</sub> [s]
1	0.0087	0.001
2	0.0163	0.065
3	0.1850	0.400

R<sub>thJK</sub> for various conduction angles d:

d	$R_{thJK}$ [K/W]
DC	0.310
180°	0.323
120°	0.333
60°	0.360
30°	0.395

Constants for  $\mathbf{Z}_{\text{thJK}}$  calculation:

i	$\mathbf{R}_{thi} \left[ K/W \right]$	<b>t</b> , [s]
1	0.0087	0.001
2	0.0163	0.065
3	0.1850	0.400
4	0.1000	1.290